Vishay Siliconix

RoHS

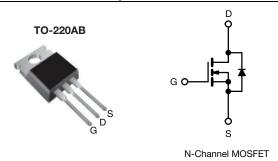
COMPLIANT

HALOGEN

FREE

E Series Power MOSFET with Fast Body Diode

PPRODUCT SUMMARY				
V _{DS} (V) at T _J max.	700			
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V	0.18		
Q _g max. (nC)	106			
Q _{gs} (nC)	14			
Q _{gd} (nC)	33			
Configuration	Single			



FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr}, Q_{rr}, and I_{RRM}
- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (C_{iss})
- Low switching losses due to reduced Q_{rr}
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High-intensity discharge (HID)
- Fluorescent ballast lighting
- Consumer and computing
- ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
 - Solar (PV inverters)
- Switch mode power supplies (SMPS)
- Applications using the following topologies
 - LCC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

ORDERING INFORMATION		
Package	TO-220AB	
Lead (Pb)-free and Halogen-free	SiHP21N65EF-GE3	

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	650	V	
Gate-Source Voltage			V_{GS}	± 30	7 °	
Continuous Drain Current (T _{.I} = 150 °C)	\/ at 10 \/	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$		21		
Continuous Drain Current (1 _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C	l _D	13	Α	
Pulsed Drain Current ^a			I _{DM}	53		
Linear Derating Factor				1.7	W/°C	
Single Pulse Avalanche Energy b			E _{AS}	367	mJ	
Maximum Power Dissipation			P _D	208	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	e Voltage Slope T _J = 125 °C		-11//-14	37	1//	
Reverse Diode dV/dt ^d			dV/dt	31	V/ns	
Soldering Recommendations (Peak Temperature) c for 10 s			300	°C		

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5.1 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.5	G/VV

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static		-					
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	650	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 1 mA	=.	0.67	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
Cata Cauraa Laglaga			V _{GS} = ± 20 V		-	± 100	nA
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 30 V	-	-	± 1	μΑ
Zava Cata Valtaga Dvain Cuwant		V _{DS} =	= 520 V, V _{GS} = 0 V	-	-	1	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 520 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	500	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A	-	0.15	0.18	Ω
Forward Transconductance	9 _{fs}	V _{DS}	= 30 V, I _D = 11 A	-	7.0	-	S
Dynamic							
Input Capacitance	C _{iss}		$V_{GS} = 0 V$,	-	2322	-	
Output Capacitance	C _{oss}	1	$V_{DS} = 100 \text{ V},$	-	105	-	1
Reverse Transfer Capacitance	C _{rss}	7	f = 1 MHz		4	-	pF
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	$V_{DS} = 0 \text{ V to } 520 \text{ V}, V_{GS} = 0 \text{ V}$		-	84	-	
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	293	-	
Total Gate Charge	Q_g		V _{GS} = 10 V		71	106	nC
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V			14	-	
Gate-Drain Charge	Q _{gd}	1		-	33	-	
Turn-On Delay Time	t _{d(on)}	V _{DD} = 520 V, I _D = 11 A,		=.	22	44	1
Rise Time	t _r			-	34	68	no
Turn-Off Delay Time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		68	102	ns
Fall Time	t _f	1		-	42	84	
Gate Input Resistance	R _g	f = 1 MHz, open drain		-	0.78	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	_
Pulsed Diode Forward Current	I _{SM}			-	-	53	_ A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	0.9	1.2	V
Reverse Recovery Time	t _{rr}		$T_J = 25 ^{\circ}\text{C}, I_F = I_S = 11 \text{A},$		160	-	ns
Reverse Recovery Charge	Q _{rr}				1.2	-	μC
Reverse Recovery Current	I _{RRM}	dI/dt = 100 A/ μ s, V _R = 25 V		-	14	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

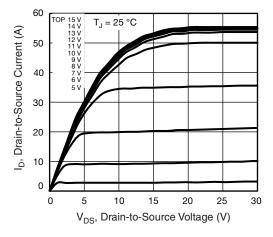


Fig. 1 - Typical Output Characteristics

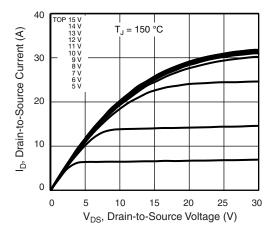


Fig. 2 - Typical Output Characteristics

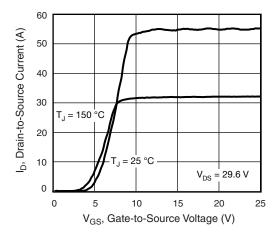


Fig. 3 - Typical Transfer Characteristics

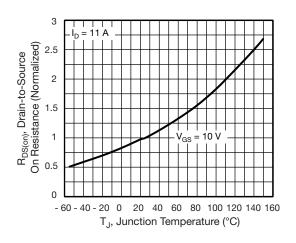


Fig. 4 - Normalized On-Resistance vs. Temperature

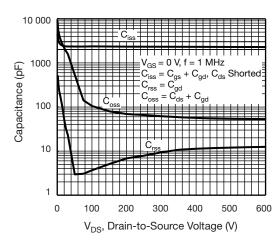


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

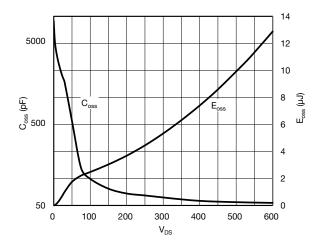


Fig. 6 - Coss and Eoss vs. VDS



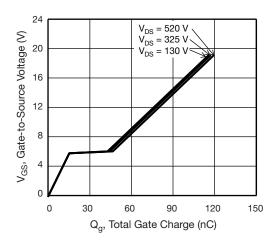


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

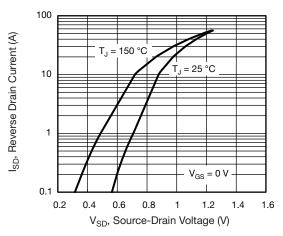


Fig. 8 - Typical Source-Drain Diode Forward Voltage

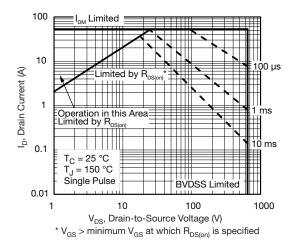


Fig. 9 - Maximum Safe Operating Area

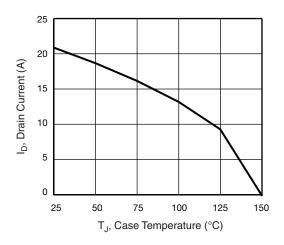


Fig. 10 - Maximum Drain Current vs. Case Temperature

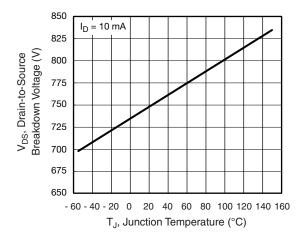


Fig. 11 - Temperature vs. Drain-to-Source Voltage



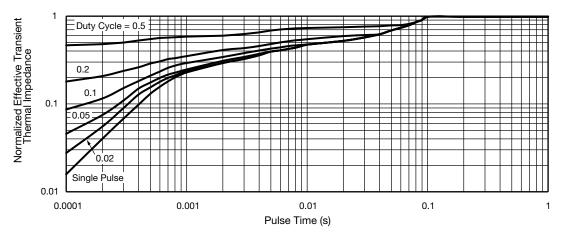


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

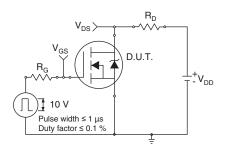


Fig. 13 - Switching Time Test Circuit

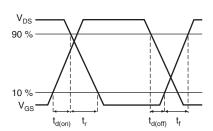


Fig. 14 - Switching Time Waveforms

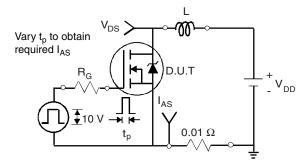


Fig. 15 - Unclamped Inductive Test Circuit

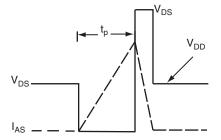


Fig. 16 - Unclamped Inductive Waveforms

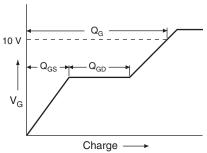


Fig. 17 - Basic Gate Charge Waveform

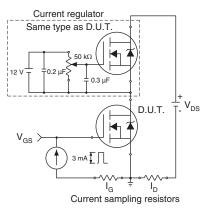
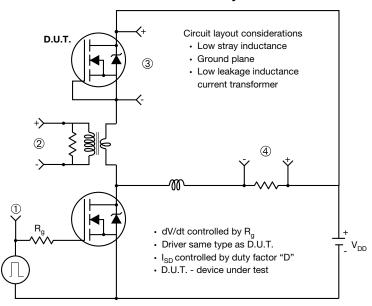


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



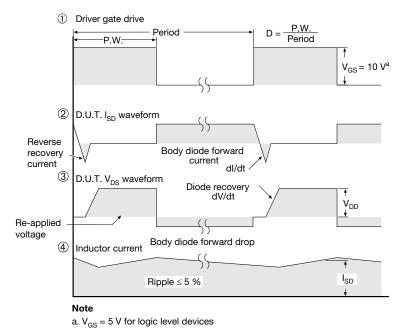


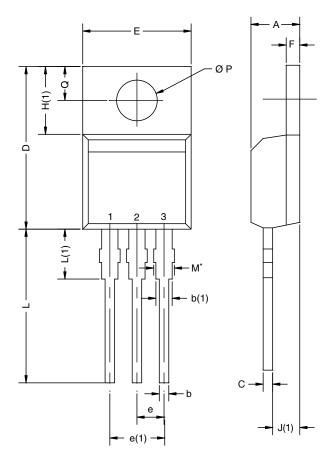
Fig. 19 - For N-Channel

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TO-220AB



	D2

	MILLIMETERS		INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
С	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
D2	12.19	12.70	0.480	0.500
Е	10.04	10.51	0.395	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
ØΡ	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118
ECN: T14-0413-Rev. P, 16-Jun-14 DWG: 5471				

Note

 $^{^{\}star}$ M = 1.32 mm to 1.62 mm (dimension including protrusion) Heatsink hole for HVM



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